

AN 130:19574 HCA  
TI **Copper alloy** having high stamping processability for  
electronic applications  
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SO Jpn. Kokai Tokkyo Koho, 8 pp.  
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	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	JP 10287939	A2	19981027	JP 1997-100279	19970417
AB	The <b>Cu alloy</b> comprises Cr 0.1-0.4, Zr .gtoreq.0 and <0.2, rare earth metal 0.002-0.2, Pb and/or Bi 0.002-0.2 wt.% (in total), and Cu bal. and the alloy has crystd. substances and <b>deposited</b> substances with diam. <3 .mu.m and crystal grain size <20 .mu.m. Alternatively, the above <b>Cu alloy</b> may also contain 0.01-1.0 wt.% Sn, Mg, Ni, <b>Ag</b> , Zn, Si, and/or Mn in total. The <b>Cu alloy</b> has high strength and cond. and is useful for lead frames for semiconductor device such as integrated circuit or for heat medium such as terminals, connectors, contacts, and so on.				

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